

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT7828469

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SANDEEP LOUIS D'SOUZA	02/13/2023
RAJ KUMAR	01/15/2023
DEEPAK RAJENDRA KARNIK	02/01/2023
REID WESTBURG	01/17/2023
KRISHNA BUSKA	02/13/2023
WILLIAM SCOFIELD	01/17/2023
GEORGE ISSA SAMAN	01/27/2023
SEONG JUN MA	02/13/2023
HUI-YA LIAO NELSON	03/03/2023
EDDIE CHOY	01/17/2023
LIVINGSTONE SONG	02/27/2023
LOUIS DOMINIC OLIVEIRA	02/01/2023

RECEIVING PARTY DATA

Name:	QUALCOMM INCORPORATED
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121-1714

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	18148006

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 5714320800

Email: docket@harrityllp.com

Correspondent Name: HARRITY & HARRITY, LLP

Address Line 1: 11350 RANDOM HILLS ROAD

Address Line 2: SUITE 600

PATENT

Address Line 4:	FAIRFAX, VIRGINIA 22030
ATTORNEY DOCKET NUMBER:	0097-4350/2300056
NAME OF SUBMITTER:	N'DEA STEWART-COLTRANE
SIGNATURE:	/N'DEA STEWART-COLTRANE/
DATE SIGNED:	03/06/2023
Total Attachments: 14 source=2300056_Assignment as filed 3 March 2023#page1.tif source=2300056_Assignment as filed 3 March 2023#page2.tif source=2300056_Assignment as filed 3 March 2023#page3.tif source=2300056_Assignment as filed 3 March 2023#page4.tif source=2300056_Assignment as filed 3 March 2023#page5.tif source=2300056_Assignment as filed 3 March 2023#page6.tif source=2300056_Assignment as filed 3 March 2023#page7.tif source=2300056_Assignment as filed 3 March 2023#page8.tif source=2300056_Assignment as filed 3 March 2023#page9.tif source=2300056_Assignment as filed 3 March 2023#page10.tif source=2300056_Assignment as filed 3 March 2023#page11.tif source=2300056_Assignment as filed 3 March 2023#page12.tif source=2300056_Assignment as filed 3 March 2023#page13.tif source=2300056_Assignment as filed 3 March 2023#page14.tif	

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ASSIGNMENT

WHEREAS, WE,

1. **Sandeep Louis D'SOUZA**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
2. **Raj KUMAR**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
3. **Deepak Rajendra KARNIK**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
4. **Reid WESTBURG**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
5. **Krishna BUSKA**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
6. **William SCOFIELD**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
7. **George Issa SAMAN**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
8. **Seong Jun MA**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
9. **Hui-Ya Liao NELSON**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
10. **Eddie CHOY**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
11. **Livingstone SONG**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,
12. **Louis Dominic OLIVEIRA**, having a mailing address located at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **ON-SCREEN KEYBOARD USER INTERFACE WITH CONTEXT-AWARE HAPTIC FEEDBACK** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign,

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convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to **U.S. Application No(s). 18/148,006** filed **December 29, 2022, Qualcomm Reference Number 2300056**, and all provisional applications relating thereto (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number (s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States or in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;


AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to me respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

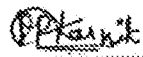
Done at San Diego, CA, United States on 02/13/2023
City, State, Country Date


Sandeep Louis D'SOUZA

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at SAN DIEGO, CA, United States on 01/15/2023 
City, State, Country Date Raj KUMAR

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

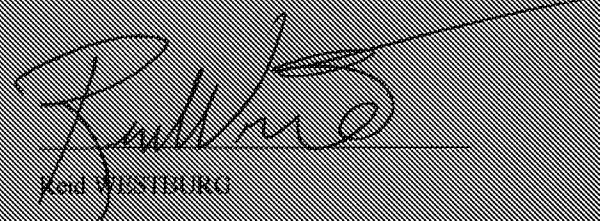
Done at	San Diego, CA, United States	on	02/01/2023	
	City, State, Country		Date	Deepak Rajendra KARNIK

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Del Mar, CA, United States on 01/17/2023

City, State, Country

Date



Kend WESTBURG

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, CA, United States on 02/13/2023
City, State, Country Date



Krishna BUSKA


AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, CA, United States on 01/17/2023
City, State, Country Date


William SCOFIELD

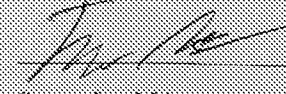
AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

San Diego, CA, United States 01/27/2023
Done at _____ on _____
City, State, Country Date



George Issa SAMAN

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

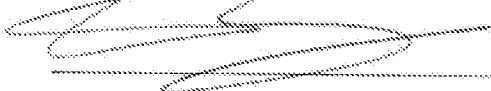
Done at San Diego, CA, United States on 02/13/2023
City, State, Country Date 
Seong Jun MA

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, CA, United States on 03/03/2023
City, State, Country Date


Hui-Ya Liao NELSON

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Carlsbad, CA, United States on 01/17/2023
City, State, Country Date 
Eddie CHOY

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, CA, United States on 02/27/2023
City, State, Country Date


Livingstone SONG

Document ID: 1673278877850 v1

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with Best interests.

San Diego, CA, United States

02/01/2023

Done at

City, State, Country

Date


Louis Dominic OLIVEIRA